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## PATENT / DOCKET NO. 5528.323

§	Notice of Allowance: 03/02/01
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

## REQUEST FOR PRINTING INFORMATION ON PATENT AND SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

BOX ISSUE FEE Commissioner For Patents Washington, DC 20231

Sir:

Pursuant to the provisions of MPEP 609, Applicant hereby makes a request to have previously cited information printed on the patent. The list of the information requested to be printed is set forth in the attached modified form PTO-1449. No inference should be made that the cited references are in fact material, are in fact prior art, or that no better art exists. The cited patents are listed in numerical order and not in any order based on their pertinence.

This Request and Supplement and Information Disclosure Statement is being filed after the mailing date of the Notice of Allowance under §1.311, but before, the payment of the Issue Fee. A fee of \$240.00 is enclosed.

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Pursuant to 37 C.F.R. §1.98(d) and MPEP 609 these references were fully Pursuant to 37 C.F.R. §1.98(d) and MPEP 609 these references were fully U.S. Serial No. 08/768,723. It is now requested that they be printed on the front of any patent issuing from this application.

The Commissioner is hereby authorized to charge any fees or credit any overpayment to the Deposit Account of Haynes and Boone, LLP 08-1394. **This form submitted in duplicate.** 

Respectfully submitted,

David L. McCombs Reg. No. 32,271

Dated: \( \simeq \) \( \lambda \) HAYNES AND BOONE, LLP

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File: 5528.323 D-896699.1 I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, Washington, D.C. 20231

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